Sponsored by IEEE Computer Society Technical Committee on Microprocessors and Microcomputers

Dear valued participant,

Each year since 1993 the IEEE Hot Interconnects Symposium has brought together designers and architects of high-performance interconnects combining academic and industry professionals. Academic and industry professionals attend this conference from around the globe which is focused on up-to-the-minute developments demonstrating leading-edge designs by engineers and researchers from throughout the world. Numerous well-known industry professionals and leaders have served as conference chair and keynote speakers, participated in panel discussions, and presented over the years.

Preparations for the 2005 IEEE Hot Interconnects conference are already underway. Included in two days of presentations will be two distinguished keynote speakers, and two controversial panel discussions, one of which immediately follows the Conference Reception Dinner on Wednesday evening. New this year is an afternoon Poster Session featuring short papers and demonstrations.

IEEE Hot Interconnects Patrons can receive immeasurably valuable visibility to its many influential attendees in numerous conference announcements (both printed and electronic), the conference proceedings package, on the conference website with a hot-linked logo, and at the Stanford conference site.

Four levels of patronage are designed to increase participation and maximize exposure to the evolving interconnects industry. When you become a patron, we work to publicize your company's name and/or logo in all aspects of the conference. Patron benefits include your company logo or name on our printed conference flyers and announcements that are distributed on university campuses across the U.S. This year we also intend to timely distribute print announcements at and on campuses worldwide. Some past participating universities have been University of Texas, Dallas; Stony Brook University; University of Arizona; Washington University, St. Louis; Virginia Tech; Princeton; Georgia Tech; Polytechnic University; Ohio State; University of Minnesota; U.C. Berkeley, and Stanford University.

Email announcements are sent to more than 30,000 targeted professionals in the electronics industry through organizational affiliations in IEEE, ACM, IEEE Computer Society, IEEE Communications Society, and academic relations announcing the program are directed to the www.hoti.org website.

To participate simply make an email indicating your desired level of participation or speak with your committee contact regarding your desired commitment level. We will then immediately post your company logo on the website and include your company name/logo in all forms of publicity. Deadline for payment is August 1, 2005. Free conference attendance is included on all 4 levels of patronage. For details please see the attached page descriptions or visit www.hoti.org/patron.

We thank you for your consideration and look forward to hearing from you.

Sincerely, IEEE Hot Interconnects Committee

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2005 IEEE Hot Interconnects Patron Program

AMERICIUM Level Patron | \$10,000+ Donation

A \$10,000 or more donation provides for the maximum exposure and participation available to a patron of the conference. This negotiable level of patronage allows us to customize a program to best suit the needs of your company with the IEEE Hot Interconnects conference.

- · Negotiable combinations
 - the number of free passes to Sessions and Tutorials
 - paid on-campus parking passes
 - table tents throughout conference site with company logo, or equivalent
 - company logo banner in conference auditorium
 - printed information page in proceedings (provided by print deadline)
 - web page on hoti.org dedicated to donating company or project
- · One 8' Conference booth table on site*
- Includes meals/breaks for up to 2 of your table attendants (the included conference passes can also be used for these individuals if they want to attend sessions)
- Company logo on attendee giveaways (if artwork submitted by July 1)
- Company provided printed advertisements inserted into attendee package
- · Company logo with hotlink on www.hoti.org website
- · Company logo on sponsor slide during session breaks
- · Company logo/name inclusion on all email advertising

PLATINUM Level Patron | \$5,000 Donation

The Platinum Patron provides the opportunity to become an active participant in the conference at the Stanford site with a table suitable for demos (with limited electricity) and use of wireless Internet access if desired. A skirted table in conference coordinated colors and 2 chairs are provided to support your equipment. Limited electrical outlets are provided.

AT THE CONFERENCE:

- Two free badge passes to IEEE Hot Interconnects 2-day Sessions
- Two 3-day on-campus Parking Passes
- One 8' Conference booth table on site with conference color coordinated table cover and skirt
- Includes meals/breaks for up to 2 of your table attendants (the included conference passes can also be used for these individuals if they want to attend sessions)
- · Company provided printed advertisements inserted into attendee package
- · Company logo with hotlink on www.hoti.org website
- · Company logo on sponsor slide during session breaks
- Company logo/name inclusion on all email advertising

ONLINE:

- · Electronic download link to your attendee advertisement (hosted on the hoti.org servers)
- --package inserts provided in pdf format by your company

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2005 IEEE Hot Interconnects Patron Program (cont'd.)

GOLD Level Patron | \$3,000 Donation

In addition to the level of exposure a patron receives in conference advertising around the globe, the Gold level receives additional exposure at the conference site with your included print advertisement in the attendee package. The attendee package comes in a reusable bag which includes conference giveaway(s) and a printed/published copy of the conference proceedings.

- · Company provided printed advertisements inserted into attendee package
- One free pass to IEEE Hot Interconnects 2-day Sessions
- · Company logo with hotlink on www.hoti.org
- Company logo on sponsor slide during session breaks
- Company logo/name inclusion on all email advertising

SILVER Level Patron | \$1,000 Donation

Silver Patron is our entry level at \$1,000 that provides global exposure in conference announcements and conference advertising in the industry and at University campuses around the world. (limited to privately-held startups, non-profit organizations, or public companies with annual revenues under \$25M)

- One free pass to IEEE Hot Interconnects 2-day Sessions
- · Company logo with hotlink on www.hoti.org
- Company logo on sponsor slide during session breaks
- · Company logo/name inclusion on all email advertising

CONTRIBUTOR (NEW) | \$500 Donation

The Contributor status was created for vendors with relevant products and services for IEEE Hot Interconnects attendees and participants. An attendant is recommended to be available to field questions about the participating company's product and/or service.

A demo and/or product sale may be made using your company supplied equipment. Note that only wireless network-based transactions are supported; no landlines or hardwired connections are available.

Level 1

· Two day Symposium only*

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- Wed 7am-5pm, Thur 7am-3pm
- · An 8' Table in the registration lobby with one chair for one attendant
- · One attendee meals/breaks
- · One electrical outlet/plug
- · 802.11b wireless Internet access

Level 2

1/2 tables are available for unattended literature only, with a \$300 donation

(NOTE: Contributor does not include Conference Reception Dinner or Conference attendance and may be purchased separately.)

Table setup time is 7:00 - 7:30 am on both days.

^{*} Tables will be picked up by event services at 3 pm on the last day of the Symposium portion of the conference. Scheduled pickup is for Thursday Aug 18, 2005.